



Powerful 3D-Inspection for In-Line Dual-Track Operation

In many respects, the S3088 DT optical 3D inspection system with dual-track operation is optimally configured for outstanding economy, speed and technical performance. Its networking capabilities were designed to enable comprehensive communication with manufacturing execution systems (MES), the line control and other machines. With the S3088 DT, electronics manufacturers are well equipped for the fully automatic processes and demanding handling concepts a fast and reliable electronic assembly inspection requires.

S3088 DT accurately captures the solder joints and components on the printed circuit board at extremely high speed. The orthogonal resolution of 10 µm/pixel ensures that even 03015 components are reliably inspected. One noteworthy feature of the 3D AOI system is its generous 50 mm by 50 mm field of view. Inspection speeds of up to 65 cm²/s can be reached. The operating software offers numerous tools for quality-oriented process control. Inspection programs can be intuitively created in the shortest time.

The system adjusts flexibly to varying track widths. If necessary, it can be used with a single track. The S3088 DT was designed for maximum ergonomics and a minimum footprint. The monitor is integrated into the system housing and especially in dense production conditions, meets the requirement to maximize accessible space.

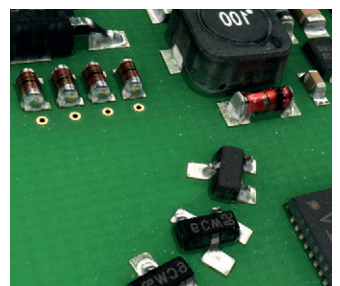
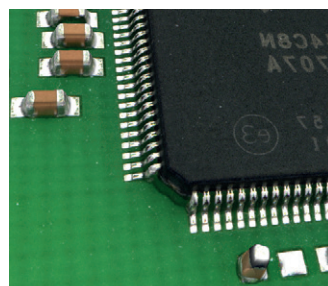
**High-throughput
3D AOI technology**

**Versatile application as dual-
or single-track system**

**Integrated monitor for
smallest footprint**

Intelligent process control tools

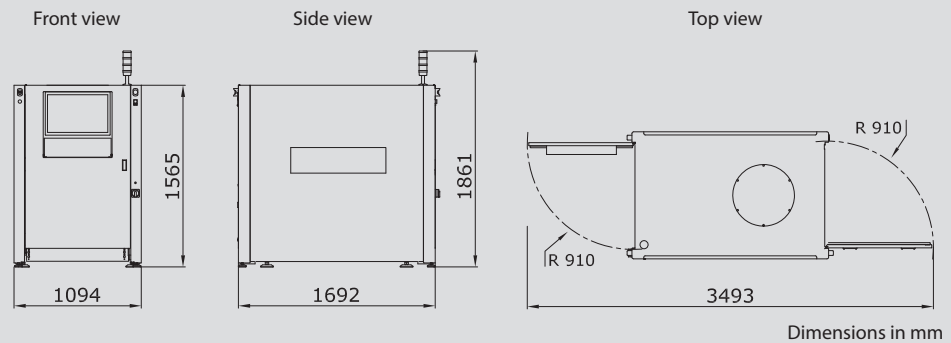
**Complete connection to
cutting-edge Industry 4.0 interfaces**



3D acquisitions for maximum overview and freely selectable perspectives with Viscom's software extension 360View

3D AOI

Technical Specifications



		S3088 DT
Inspection scope	3D AOI	Solder joints, placement, solder paste
Camera technology*	3D camera technology	
	Z-resolution	0.5 µm
	Z-range	Up to 30 mm (1.2")
	Angled view cameras	
	Number of megapixel cameras	8
Orthogonal camera		
	Resolution	10 µm
	Field of view	50 mm x 50 mm (2" x 2")
Software	User interface	Viscom EasyPro/vVision-ready
	Statistical process control	Viscom SPC, open interface (optional)
	Verification station	Viscom HARAN/vVerify-ready
	Remote diagnosis	Viscom SRC (software remote control) (optional)
	Programming station	Viscom PST34 (optional)
System computer	Operating system	Windows®
	Processor	Intel® Core™ i7
PCB handling	Transport type	Dual-track transport
	PCB dimensions (L x W)	450 mm x 350 mm (17.7" x 13.8"), minimum width 70 mm (2.8")
	Transport height	900 - 950 mm ± 20 mm (35.4" - 37.4" ± 0.8")
	Width adjustment	Automatic**
	PCB clamping	Pneumatic
	Upper transport clearance (max)	50 mm (2")
Lower transport clearance	40 mm (1.6")**	
Inspection speed		Up to 65 cm ² /s
Other system data	Positioning/handling unit	Synchronous linear motors
	Interfaces	SMEMA (other interfaces on request)
	Power requirements	400 V (other voltages on request), 3P/N/PE, 8 A, compressed air max. 10 bar (working pressure 4 - 6 bar)
	System dimensions	1094 mm x 1565 mm x 1692 mm (43.1" x 61.6" x 66.6") (W x H x D)
	Weight	1400 kg (3086 lbs)

*Standard configuration, other camera technologies on request.

**Various width adjustments or clearance heights on request.